Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	516
Number of Logic Elements/Cells	8256
Total RAM Bits	165888
Number of I/O	138
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	208-BFQFP
Supplier Device Package	208-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep2c8q208c7n

protocols. Visit the Altera IPMegaStore at www.altera.com to download IP MegaCore functions.

- Nios II Embedded Processor support

The Cyclone II family offers devices with the Fast-On feature, which offers a faster power-on-reset (POR) time. Devices that support the Fast-On feature are designated with an "A" in the device ordering code. For example, EP2C5A, EP2C8A, EP2C15A, and EP2C20A. The EP2C5A is only available in the automotive speed grade. The EP2C8A and EP2C20A are only available in the industrial speed grade. The EP2C15A is only available with the Fast-On feature and is available in both commercial and industrial grades. The Cyclone II "A" devices are identical in feature set and functionality to the non-A devices except for support of the faster POR time.

Cyclone II A devices are offered in automotive speed grade. For more information, refer to the Cyclone II section in the *Automotive-Grade Device Handbook*.

For more information on POR time specifications for Cyclone II A and non-A devices, refer to the *Hot Socketing & Power-On Reset* chapter in the *Cyclone II Device Handbook*.

Table 1–1 lists the Cyclone II device family features. Table 1–2 lists the Cyclone II device package offerings and maximum user I/O pins.

Table 1–1. Cyclone II FPGA Family Features (Part 1 of 2)

Feature	EP2C5 *(2)*	EP2C8 *(2)*	EP2C15 *(1)*	EP2C20 *(2)*	EP2C35	EP2C50	EP2C70
LEs	4,608	8,256	14,448	18,752	33,216	50,528	68,416
M4K RAM blocks (4 Kbits plus 512 parity bits	26	36	52	52	105	129	250
Total RAM bits	119,808	165,888	239,616	239,616	483,840	594,432	1,152,000
Embedded multipliers *(3)*	13	18	26	26	35	86	150
PLLs	2	2	4	4	4	4	4

Table 2–4 describes the PLL features in Cyclone II devices.

Table 2–4. Cyclone II PLL Features

Feature	Description
Clock multiplication and division	*m* / (*n* × post-scale counter) *m* and post-scale counter values (C0 to C2) range from 1 to 32. *n* ranges from 1 to 4.
Phase shift	Cyclone II PLLs have an advanced clock shift capability that enables programmable phase shifts in increments of at least 45°. The finest resolution of phase shifting is determined by the voltage control oscillator (VCO) period divided by 8 (for example, 1/1000 MHz/8 = down to 125-ps increments).
Programmable duty cycle	The programmable duty cycle allows PLLs to generate clock outputs with a variable duty cycle. This feature is supported on each PLL post-scale counter (C0-C2).
Number of internal clock outputs	The Cyclone II PLL has three outputs which can drive the global clock network. One of these outputs (C2) can also drive a dedicated PLL<#>_OUT pin (single ended or differential).
Number of external clock outputs	The C2 output drives a dedicated PLL<#>_OUT pin. If the C2 output is not used to drive an external clock output, it can be used to drive the internal global clock network. The C2 output can concurrently drive the external clock output and internal global clock network.
Manual clock switchover	The Cyclone II PLLs support manual switchover of the reference clock through internal logic. This enables you to switch between two reference input clocks during user mode for applications that may require clock redundancy or support for clocks with two different frequencies.
Gated lock signal	The lock output indicates that there is a stable clock output signal in phase with the reference clock. Cyclone II PLLs include a programmable counter that holds the lock signal low for a user-selected number of input clock transitions, allowing the PLL to lock before enabling the locked signal. Either a gated locked signal or an ungated locked signal from the locked port can drive internal logic or an output pin.
Clock feedback modes	In zero delay buffer mode, the external clock output pin is phase-aligned with the clock input pin for zero delay. In normal mode, the PLL compensates for the internal global clock network delay from the input clock pin to the clock port of the IOE output registers or registers in the logic array. In no compensation mode, the PLL does not compensate for any clock networks.
Control signals	The pllenable signal enables and disables the PLLs. The areset signal resets/resynchronizes the inputs for each PLL. The pfdena signal controls the phase frequency detector (PFD) output with a programmable gate.

Table 5–3. DC Characteristics for User I/O, Dual-Purpose, and Dedicated Pins (Part 1 of 2)

Symbol	Parameter	Conditions		Minimum	Typical	Maximum	Unit
V_{IN}	Input voltage	*(1)*, *(2)*		–0.5	—	4.0	V
I_i	Input pin leakage current	$V_{IN} = V_{CCIOmax}$ to 0 V *(3)*		–10	—	10	µA
V_{OUT}	Output voltage	—		0	—	V_{CCIO}	V
I_{OZ}	Tri-stated I/O pin leakage current	$V_{OUT} = V_{CCIOmax}$ to 0 V *(3)*		–10	—	10	µA
I_{CCINT0}	V_{CCINT} supply current (standby)	V_{IN} = ground, no load, no toggling inputs T_J = 25° C Nominal V_{CCINT}	EP2C5/A	—	0.010	*(4)*	A
			EP2C8/A	—	0.017	*(4)*	A
			EP2C15A	—	0.037	*(4)*	A
			EP2C20/A	—	0.037	*(4)*	A
			EP2C35	—	0.066	*(4)*	A
			EP2C50	—	0.101	*(4)*	A
			EP2C70	—	0.141	*(4)*	A
I_{CCIO0}	V_{CCIO} supply current (standby)	V_{IN} = ground, no load, no toggling inputs T_J = 25° C V_{CCIO} = 2.5 V	EP2C5/A	—	0.7	*(4)*	mA
			EP2C8/A	—	0.8	*(4)*	mA
			EP2C15A	—	0.9	*(4)*	mA
			EP2C20/A	—	0.9	*(4)*	mA
			EP2C35	—	1.3	*(4)*	mA
			EP2C50	—	1.3	*(4)*	mA
			EP2C70	—	1.7	*(4)*	mA

Table 5–8 shows the recommended operating conditions for user I/O pins with differential I/O standards.

Table 5–8. Recommended Operating Conditions for User I/O Pins Using Differential Signal I/O Standards

I/O Standard	V_{CCIO} (V)			V_{ID} (V) *(1)*			V_{ICM} (V)			V_{IL} (V)		V_{IH} (V)	
	Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	Min	Max	Min	Max
LVDS	2.375	2.5	2.625	0.1	—	0.65	0.1	—	2.0	—	—	—	—
Mini-LVDS *(2)*	2.375	2.5	2.625	—	—	—	—	—	—	—	—	—	—
RSDS *(2)*	2.375	2.5	2.625	—	—	—	—	—	—	—	—	—	—
LVPECL *(3) (6)*	3.135	3.3	3.465	0.1	0.6	0.95	—	—	—	0	2.2	2.1	2.88
Differential 1.5-V HSTL class I and II *(4)*	1.425	1.5	1.575	0.2	—	V_{CCIO} + 0.6	0.68	—	0.9	—	V_{REF} – 0.20	V_{REF} + 0.20	—
Differential 1.8-V HSTL class I and II *(4)*	1.71	1.8	1.89	—	—	—	—	—	—	—	V_{REF} – 0.20	V_{REF} + 0.20	—
Differential SSTL-2 class I and II *(5)*	2.375	2.5	2.625	0.36	—	V_{CCIO} + 0.6	0.5 × V_{CCIO} – 0.2	0.5 × V_{CCIO}	0.5 × V_{CCIO} + 0.2	—	V_{REF} – 0.35	V_{REF} + 0.35	—
Differential SSTL-18 class I and II *(5)*	1.7	1.8	1.9	0.25	—	V_{CCIO} + 0.6	0.5 × V_{CCIO} – 0.2	0.5 × V_{CCIO}	0.5 × V_{CCIO} + 0.2	—	V_{REF} – 0.25	V_{REF} + 0.25	—

Notes to Table 5–8:

(1) Refer to the *High-Speed Differential Interfaces in Cyclone II Devices* chapter of the *Cyclone II Device Handbook* for measurement conditions on V_{ID}.

(2) The RSDS and mini-LVDS I/O standards are only supported on output pins.

(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(4) The differential 1.8-V and 1.5-V HSTL I/O standards are only supported on clock input pins and PLL output clock pins.

(5) The differential SSTL-18 and SSTL-2 I/O standards are only supported on clock input pins and PLL output clock pins.

(6) The LVPECL clock inputs are powered by V_{CCINT} and support all V_{CCIO} settings. However, it is recommended to connect V_{CCIO} to typical value of 3.3V.

Table 5–13 shows the Cyclone II device pin capacitance for different I/O pin types.

Table 5–13. Device Capacitance *Note (1)*

Symbol	Parameter	Typical	Unit
C_{IO}	Input capacitance for user I/O pin.	6	pF
C_{LVDS}	Input capacitance for dual-purpose LVDS/user I/O pin.	6	pF
C_{VREF}	Input capacitance for dual-purpose VREF pin when used as VREF or user I/O pin.	21	pF
C_{CLK}	Input capacitance for clock pin.	5	pF

Note to Table 5–13:

(1) Capacitance is sample-tested only. Capacitance is measured using time-domain reflectometry (TDR). Measurement accuracy is within ±0.5 pF.

Power Consumption

You can calculate the power usage for your design using the PowerPlay Early Power Estimator and the PowerPlay Power Analyzer feature in the Quartus® II software.

The interactive PowerPlay Early Power Estimator is typically used during the early stages of FPGA design, prior to finalizing the project, to get a magnitude estimate of the device power. The Quartus II software PowerPlay Power Analyzer feature is typically used during the later stages of FPGA design. The PowerPlay Power Analyzer also allows you to apply test vectors against your design for more accurate power consumption modeling.

In both cases, only use these calculations as an estimation of power, not as a specification. For more information on PowerPlay tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *Power Estimation and Analysis* section in volume 3 of the *Quartus II Handbook*.

You can obtain the Excel-based PowerPlay Early Power Estimator at www.altera.com. Refer to Table 5–3 on page 5–3 for typical I_{CC} standby specifications.

The power-up current required by Cyclone II devices does not exceed the maximum static current. The rate at which the current increases is a function of the system power supply. The exact amount of current consumed varies according to the process, temperature, and power ramp rate. The duration of the I_{CCINT} power-up requirement depends on the V_{CCINT} voltage supply rise time.

Table 5–16. LE_FF Internal Timing Microparameters (Part 2 of 2)

Parameter	–6 Speed Grade (1)		–7 Speed Grade (2)		–8 Speed Grade (3)		Unit
	Min	Max	Min	Max	Min	Max	
TPRE	191	—	244	—	244	—	ps
	—	—	217	—	244	—	ps
TCLKL	1000	—	1242	—	1242	—	ps
	—	—	1111	—	1242	—	ps
TCLKH	1000	—	1242	—	1242	—	ps
	—	—	1111	—	1242	—	ps
tLUT	180	438	172	545	172	651	ps
	—	—	180	—	180	—	ps

Notes to Table 5–16:

(1) For the –6 speed grades, the minimum timing is for the commercial temperature grade. The –7 speed grade devices offer the automotive temperature grade. The –8 speed grade devices offer the industrial temperature grade.

(2) For each parameter of the –7 speed grade columns, the value in the first row represents the minimum timing parameter for automotive devices. The second row represents the minimum timing parameter for commercial devices.

(3) For each parameter of the –8 speed grade columns, the value in the first row represents the minimum timing parameter for industrial devices. The second row represents the minimum timing parameter for commercial devices.

Table 5–17. IOE Internal Timing Microparameters (Part 1 of 2)

Parameter	–6 Speed Grade (1)		–7 Speed Grade (2)		–8 Speed Grade (3)		Unit
	Min	Max	Min	Max	Min	Max	
TSU	76	—	101	—	101	—	ps
	—	—	89	—	101	—	ps
TH	88	—	106	—	106	—	ps
	—	—	97	—	106	—	ps
TCO	99	155	95	171	95	187	ps
	—	—	99	—	99	—	ps
TPIN2COMBOUT_R	384	762	366	784	366	855	ps
	—	—	384	—	384	—	ps
TPIN2COMBOUT_C	385	760	367	783	367	854	ps
	—	—	385	—	385	—	ps
TCOMBIN2PIN_R	1344	2490	1280	2689	1280	2887	ps
	—	—	1344	—	1344	—	ps

Table 5–41. Cyclone II I/O Input Delay for Row Pins (Part 2 of 2)

I/O Standard	Parameter	Fast Corner		–6 Speed Grade	–7 Speed Grade (1)	–7 Speed Grade (2)	–8 Speed Grade	Unit
		Industrial/ Automotive	Commer -cial					
1.5V_HSTL_CLASS_II	t_{PI}	593	621	1051	1109	1167	1167	ps
	t_{PCOUT}	376	394	684	733	782	782	ps
1.8V_HSTL_CLASS_I	t_{PI}	581	609	933	967	1004	1004	ps
	t_{PCOUT}	364	382	566	591	619	619	ps
1.8V_HSTL_CLASS_II	t_{PI}	581	609	933	967	1004	1004	ps
	t_{PCOUT}	364	382	566	591	619	619	ps
DIFFERENTIAL_SSTL_2_ CLASS_I	t_{PI}	536	561	896	947	998	998	ps
	t_{PCOUT}	319	334	529	571	613	613	ps
DIFFERENTIAL_SSTL_2_ CLASS_II	t_{PI}	536	561	896	947	998	998	ps
	t_{PCOUT}	319	334	529	571	613	613	ps
DIFFERENTIAL_SSTL_18_ CLASS_I	t_{PI}	581	609	933	967	1004	1004	ps
	t_{PCOUT}	364	382	566	591	619	619	ps
DIFFERENTIAL_SSTL_18_ CLASS_II	t_{PI}	581	609	933	967	1004	1004	ps
	t_{PCOUT}	364	382	566	591	619	619	ps
1.8V_DIFFERENTIAL_HSTL_ CLASS_I	t_{PI}	581	609	933	967	1004	1004	ps
	t_{PCOUT}	364	382	566	591	619	619	ps
1.8V_DIFFERENTIAL_HSTL_ CLASS_II	t_{PI}	581	609	933	967	1004	1004	ps
	t_{PCOUT}	364	382	566	591	619	619	ps
1.5V_DIFFERENTIAL_HSTL_ CLASS_I	t_{PI}	593	621	1051	1109	1167	1167	ps
	t_{PCOUT}	376	394	684	733	782	782	ps
1.5V_DIFFERENTIAL_HSTL_ CLASS_II	t_{PI}	593	621	1051	1109	1167	1167	ps
	t_{PCOUT}	376	394	684	733	782	782	ps
LVDS	t_{PI}	651	682	1036	1075	1113	1113	ps
	t_{PCOUT}	434	455	669	699	728	728	ps
PCI	t_{PI}	595	623	1113	1156	1232	1232	ps
	t_{PCOUT}	378	396	746	780	847	847	ps
PCI-X	t_{PI}	595	623	1113	1156	1232	1232	ps
	t_{PCOUT}	378	396	746	780	847	847	ps

Notes to Table 5–41 :

(1) These numbers are for commercial devices.

(2) These numbers are for automotive devices.

Table 5–53 shows the JTAG timing parameters and values for Cyclone II devices.

Table 5–53. Cyclone II JTAG Timing Parameters and Values

Symbol	Parameter	Min	Max	Unit
t_{JCP}	TCK clock period	40	—	ns
t_{JCH}	TCK clock high time	20	—	ns
t_{JCL}	TCK clock low time	20	—	ns
t_{JPSU}	JTAG port setup time *(2)*	5	—	ns
t_{JPH}	JTAG port hold time	10	—	ns
t_{JPCO}	JTAG port clock to output *(2)*	—	13	ns
t_{JPZX}	JTAG port high impedance to valid output *(2)*	—	13	ns
t_{JPXZ}	JTAG port valid output to high impedance *(2)*	—	13	ns
t_{JSSU}	Capture register setup time *(2)*	5	—	ns
t_{JSH}	Capture register hold time	10	—	ns
t_{JSCO}	Update register clock to output	—	25	ns
t_{JSZX}	Update register high impedance to valid output	—	25	ns
t_{JSXZ}	Update register valid output to high impedance	—	25	ns

Notes to Table 5–53:

(1) This information is preliminary.

(2) This specification is shown for 3.3-V LVTTL/LVCMOS and 2.5-V LVTTL/LVCMOS operation of the JTAG pins. For 1.8-V LVTTL/LVCMOS and 1.5-V LVCMOS, the JTAG port and capture register clock setup time is 3 ns and port clock to output time is 15 ns.

Cyclone II devices must be within the first 17 devices in a JTAG chain. All of these devices have the same JTAG controller. If any of the Cyclone II devices are in the 18th position or after they will fail configuration. This does not affect the SignalTap® II logic analyzer.

For more information on JTAG, refer to the *IEEE 1149.1 (JTAG) Boundary-Scan Testing for Cyclone II Devices* chapter in the *Cyclone II Handbook*.

Table 7–6. I/O Standards Supported for Cyclone II PLLs (Part 2 of 2)

I/O Standard	Input	Output	
	inclk	lock	pll_out
SSTL-25 class II	✓	✓	✓
RSDS/mini-LVDS *(4)*		✓	✓

Notes to Table 7–6:
(1) The PCI-X I/O standard is supported only on side I/O pins.
(2) Differential SSTL and HSTL outputs are only supported on the PLL<#>_OUT pins.
(3) These I/O standards are only supported on top and bottom I/O pins.
(4) The RSDS and mini-LVDS pins are only supported on output pins.

Clock Feedback Modes

Cyclone II PLLs support four clock feedback modes: normal mode, zero delay buffer mode, no compensation mode, and source synchronous mode. Cyclone II PLLs do not have support for external feedback mode. All the supported clock feedback modes allow for multiplication and division, phase shifting, and programmable duty cycle. The phase relationships shown in the waveforms in Figures 7–4 through 7–6 are for the default (zero degree) phase shift setting. Changing the phase-shift setting changes the relationships between the output clocks from the PLL.

Normal Mode

In normal mode, the PLL phase-aligns the input reference clock with the clock signal at the ports of the registers in the logic array I/O registers to compensate for the internal global clock network delay. Use the `altpll` megafunction in the Quartus II software to define which internal clock output from the PLL (c0, c1, or c2) to compensate for.

If an external clock output pin (PLL<#>_OUT) is used in this mode, there is a phase shift with respect to the clock input pin. Similarly, if the internal PLL clock outputs are used to drive general-purpose I/O pins, there is be phase shift with respect to the clock input pin.

Figure 7–4 shows an example waveform of the PLL clocks' phase relationship in this mode.

Table 7–9. Clock Control Block Inputs (Part 2 of 2)

Input	Description
PLL outputs	The PLL counter outputs can drive the global clock network.
Internal logic	The global clock network can also be driven through the logic array routing to enable internal logic (LEs) to drive a high fan-out, low skew signal path.

In Cyclone II devices, the dedicated clock input pins, PLL counter outputs, dual-purpose clock I/O inputs, and internal logic can all feed the clock control block for each global clock network. The output from the clock control block in turn feeds the corresponding global clock network. The clock control blocks are arranged on the device periphery and there are a maximum of 16 clock control blocks available per Cyclone II device.

The control block has two functions:

- Dynamic global clock network clock source selection
- Global clock network power-down (dynamic enable and disable)

Figure 7–11 shows the clock control block.

You can use any of the user I/O pins for commands and addresses. Because of the symmetrical setup and hold time for the command and address pins at the memory device, you may need to generate these signals from the negative edge of the system clock.

The clocks to the SDRAM device are called CK and CK#. Use any of the user I/O pins via the DDR registers to generate the CK and CK# signals to meet the t_{DQSS} requirements of the DDR SDRAM or DDR2 SDRAM device. The memory device's t_{DQSS} requires the positive edge of the write DQS signal to be within 25% of the positive edge of the DDR SDRAM and DDR2 SDRAM clock input. Because of strict skew requirements between CK and CK# signals, use adjacent pins to generate the clock pair. Surround the pair with buffer pins tied to V_{CC} and pins tied to ground for better noise immunity from other signals.

Read & Write Operation

When reading from the memory, DDR and DDR2 SDRAM devices send the data edge-aligned relative to the data strobe. To properly read the data, the data strobe must be center-aligned relative to the data inside the FPGA. Cyclone II devices feature clock delay control circuitry to shift the data strobe to the middle of the data window. Figure 9–1 shows an example of how the memory sends out the data and data strobe for a burst-of-two operation.

Cyclone II DDR Memory Support Overview

Table 9–1 shows the external memory interfaces supported in Cyclone II devices.

Table 9–1. External Memory Support in Cyclone II Devices *Note (1)*

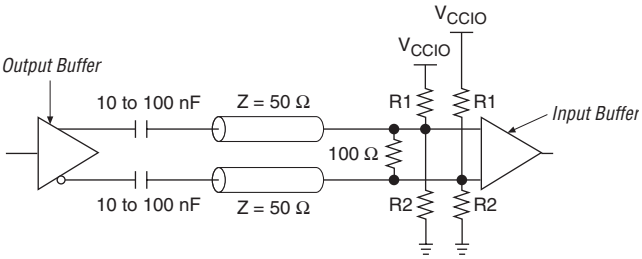
Memory Standard	I/O Standard	Maximum Bus Width	Maximum Clock Rate Supported (MHz)	Maximum Data Rate Supported (Mbps)
DDR SDRAM	SSTL-2 class I *(2)*	72	167	333 *(1)*
	SSTL-2 class II *(2)*	72	133	267 *(1)*
DDR2 SDRAM	SSTL-18 class I *(2)*	72	167	333 *(1)*
	SSTL-18 class II *(3)*	72	125	250 *(1)*
QDRII SRAM *(4)*	1.8-V HSTL class I *(2)*	36	167	667 *(1)*
	1.8-V HSTL class II *(3)*	36	100	400 *(1)*

Notes to Table 9–1:

(1) The data rate is for designs using the clock delay control circuitry.
(2) These I/O standards are supported on all the I/O banks of the Cyclone II device.
(3) These I/O standards are supported only on the I/O banks on the top and bottom of the Cyclone II device.
(4) For maximum performance, Altera recommends using the 1.8-V HSTL I/O standard because of higher I/O drive strength. QDRII SRAM devices also support the 1.5-V HSTL I/O standard.

Cyclone II devices support the data strobe or read clock signal (DQS) used in DDR SDRAM with the clock delay control circuitry that can shift the incoming DQS signals to center them within the data window. To achieve DDR operation, the DDR input and output registers are implemented using the internal logic element (LE) registers. You should use the `altdqs` and `altdq` megafunctions in the Quartus II software to implement the DDR registers used for DQS and DQ signals, respectively.

Figure 10–18. LVPECL AC Coupled Termination



Cyclone II I/O Banks

The I/O pins on Cyclone II devices are grouped together into I/O banks, and each bank has a separate power bus. This allows you to select the preferred I/O standard for a given bank, enabling tremendous flexibility in the Cyclone II device's I/O support.

EP2C5 and EP2C8 devices support four I/O banks. EP2C15, EP2C20, EP2C35, EP2C50, and EP2C70 devices support eight I/O banks. Each device I/O pin is associated with one of these specific, numbered I/O banks (refer to Figures 10–19 and 10–20). To accommodate voltage-referenced I/O standards, each Cyclone II I/O bank has separate V_{REF} bus. Each bank in EP2C5, EP2C8, EP2C15, EP2C20, EP2C35, and EP2C50 devices supports two `VREF` pins and each bank in EP2C70 devices supports four `VREF` pins. In the event these pins are not used as `VREF` pins, they may be used as regular I/O pins. However, they are expected to have slightly higher pin capacitance than other user I/O pins when used with regular user I/O pins.

Table 10–5. Cyclone II Regular I/O Standards Support

I/O Standard	I/O Banks for EP2C15, EP2C20, EP2C35, EP2C50 and EP2C70 Devices								I/O Banks for EP2C5 and EP2C8 Devices			
	1	2	3	4	5	6	7	8	1	2	3	4
LVTTL	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
LVCMOS	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
2.5 V	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
1.8 V	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
1.5 V	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
3.3-V PCI	✓	✓	—	—	✓	✓	—	—	✓	—	✓	—
3.3-V PCI-X	✓	✓	—	—	✓	✓	—	—	✓	—	✓	—
SSTL-2 class I	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
SSTL-2 class II	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
SSTL-18 class I	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
SSTL-18 class II	*(1)*	*(1)*	✓	✓	*(1)*	*(1)*	✓	✓	*(1)*	✓	*(1)*	✓
1.8-V HSTL class I	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
1.8-V HSTL class II	*(1)*	*(1)*	✓	✓	*(1)*	*(1)*	✓	✓	*(1)*	✓	*(1)*	✓
1.5-V HSTL class I	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
1.5-V HSTL class II	*(1)*	*(1)*	✓	✓	*(1)*	*(1)*	✓	✓	*(1)*	✓	*(1)*	✓
Pseudo-differential SSTL-2	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*
Pseudo-differential SSTL-18	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*
1.8-V pseudo-differential HSTL	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*
1.5-V pseudo-differential HSTL	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*	*(2)*
LVDS	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓	✓
RSDS and mini-LVDS	*(3)*	*(3)*	*(3)*	*(3)*	*(3)*	*(3)*	*(3)*	*(3)*	*(3)*	*(3)*	*(3)*	*(3)*
Differential LVPECL	*(4)*	*(4)*	*(4)*	*(4)*	*(4)*	*(4)*	*(4)*	*(4)*	*(4)*	*(4)*	*(4)*	*(4)*

Notes to Table 10–5:

(1) These I/O banks support SSTL-18 class II and 1.8- and 1.5-V HSTL class II inputs.

(2) Pseudo-differential I/O standards are only supported for clock inputs and dedicated `PLL_OUT` outputs. Refer to Table 10–1 for more information.

(3) This I/O standard is only supported for outputs.

(4) This I/O standard is only supported for the clock inputs.

Table 10–12. Cyclone II I/O Standard DC Current Specification (Preliminary) (Part 2 of 2)

I/O Standard	I_{PIN} (mA)	
	Top and Bottom Banks	Side Banks
1.5-V differential HSTL class II *(3)*	16 *(4)*	
LVDS, RSDS and mini-LVDS	12	12

Notes to Table 10–12:

(1) The DC power specification of each I/O standard depends on the current sourcing and sinking capabilities of the I/O buffer programmed with that standard, as well as the load being driven. LVTTL and LVCMOS, and 2.5-, 1.8-, and 1.5-V outputs are not included in the static power calculations because they normally do not have resistor loads in real applications. The voltage swing is rail-to-rail with capacitive load only. There is no DC current in the system.

(2) This I_{PIN} value represents the DC current specification for the default current strength of the I/O standard. The I_{PIN} varies with programmable drive strength and is the same as the drive strength as set in Quartus II software. Refer to the *Cyclone II Architecture* chapter in volume 1 of the *Cyclone II Device Handbook* for more information on the programmable drive strength feature of voltage referenced I/O standards.

(3) The current value obtained for differential HSTL and differential SSTL standards is per pin and not per differential pair, as opposed to the per-pair current value of LVDS standard.

(4) This I/O standard is only supported for clock input pins and `PLL_OUT` pins.

Table 10–12 only shows the limit on the static power consumed by an I/O standard. The amount of total power used at any moment could be much higher, and is based on the switching activities.

5.0-V Device Compatibility

A Cyclone II device may not correctly interoperate with a 5.0-V device if the output of the Cyclone II device is connected directly to the input of the 5.0-V device. If V_{OUT} of the Cyclone II device is greater than V_{CCIO}, the PMOS pull-up transistor still conducts if the pin is driving high, preventing an external pull-up resistor from pulling the signal to 5.0-V.

A Cyclone II device can drive a 5.0-V LVTTL device by connecting the V_{CCIO} pins of the Cyclone II device to 3.3 V. This is because the output high voltage (V_{OH}) of a 3.3-V interface meets the minimum high-level voltage of 2.4-V of a 5.0-V LVTTL device. (A Cyclone II device cannot drive a 5.0-V LVCMOS device.)

Because the Cyclone II devices are 3.3-V, 64- and 32-bit, 66- and 33-MHz PCI and 64-bit 133-MHz PCI-X compliant, the input circuitry accepts a maximum high-level input voltage (V_{IH}) of 4.1-V. To drive a Cyclone II device with a 5.0-V device, you must connect a resistor (R_2) between the Cyclone II device and the 5.0-V device. Refer to Figure 10–21.

- Maintain equal distance between traces in LVDS pairs, as much as possible. Routing the pair of traces close to each other maximizes the common-mode rejection ratio (CMRR).
- Longer traces have more inductance and capacitance. These traces should be as short as possible to limit signal integrity issues.
- Place termination resistors as close to receiver input pins as possible.
- Use surface mount components.
- Avoid 90° or 45° corners.
- Use high-performance connectors.
- Design backplane and card traces so that trace impedance matches the connector's and/or the termination's impedance.
- Keep equal number of vias for both signal traces.
- Create equal trace lengths to avoid skew between signals. Unequal trace lengths result in misplaced crossing points and decrease system margins as the channel-to-channel skew (TCCS) value increases.
- Limit vias because they cause discontinuities.
- Use the common bypass capacitor values such as 0.001, 0.01, and 0.1 µF to decouple the high-speed PLL power and ground planes.
- Keep switching transistor-to-transistor logic (TTL) signals away from differential signals to avoid possible noise coupling.
- Do not route TTL clock signals to areas under or above the differential signals.
- Analyze system-level signals.

For PCB layout guidelines, see *AN 224: High-Speed Board Layout Guidelines*.

Conclusion

Cyclone II differential I/O capabilities enable you to keep pace with increasing design complexity. Support for I/O standards including LVDS, LVPECL, RSDS, mini-LVDS, differential SSTL and differential HSTL allows Cyclone II devices to fit into a wide variety of applications. Taking advantage of these I/O capabilities and Cyclone II pricing allows you to lower your design costs while remaining on the cutting edge of technology.

data A signal through a register and send the data B signal directly to the multiplier). The following control signals are available to each register within the embedded multiplier:

- clock
- clock enable
- asynchronous clear

All input and output registers within a single embedded multiplier are fed by the same clock, clock enable, or asynchronous clear signal.

Multiplier Stage

The multiplier stage supports 9 × 9 or 18 × 18 multipliers as well as other smaller multipliers in between these configurations. See "Operational Modes" on page 12–6 for details. Depending on the data width or operational mode of the multiplier, a single embedded multiplier can perform one or two multiplications in parallel.

Each multiplier operand can be a unique signed or unsigned number. Two signals, `signa` and `signb`, control whether a multiplier's input is a signed or unsigned value. If the `signa` signal is high, the data A operand is a signed number, and if the `signa` signal is low, the data A operand is an unsigned number. Table 12–3 shows the sign of the multiplication result for the various operand sign representations. The result of the multiplication is signed if any one of the operands is a signed value.

Table 12–3. Multiplier Sign Representation

Data A		Data B		Result
signa Value	Logic Level	signb Value	Logic Level	
Unsigned	Low	Unsigned	Low	Unsigned
Unsigned	Low	Signed	High	Signed
Signed	High	Unsigned	Low	Signed
Signed	High	Signed	High	Signed

There is only one `signa` and one `signb` signal for each embedded multiplier. The `signa` and `signb` signals can be changed dynamically to modify the sign representation of the input operands at run time. You can send the `signa` and `signb` signals through a dedicated input register. The multiplier offers full precision regardless of the sign representation.

For more information on configuration issues, see the *Debugging Configuration Problems* chapter of the *Configuration Handbook* and the FPGA Configuration Troubleshooter on the Altera web site (**www.altera.com**).

Multiple Device AS Configuration

You can configure multiple Cyclone II devices using a single serial configuration device. You can cascade multiple Cyclone II devices using the chip-enable (nCE) and chip-enable-out (nCEO) pins. Connect the nCE pin of the first device in the chain to ground and connect the nCEO pin to the nCE pin of the next device in the chain. Use an external 10-kΩ pull-up resistor to pull the nCEO signal high to its V_{CCIO} level to help the internal weak pull-up resistor. When the first device captures all of its configuration data from the bitstream, it transitions its nCEO pin low, initiating the configuration of the next device in the chain. You can leave the nCEO pin of the last device unconnected or use it as a user I/O pin after configuration if the last device in chain is a Cyclone II device.

The Quartus II software sets the Cyclone II device nCEO pin as an output pin driving to ground by default. If the device is in a chain, and the nCEO pin is connected to the next device's nCE pin, you must make sure that the nCEO pin is not used as a user I/O pin after configuration. The software setting is in the **Dual-Purpose Pins** tab of the **Device & Pin Options** dialog box in Quartus II software.

The first Cyclone II device in the chain is the configuration master and controls the configuration of the entire chain. Select the AS configuration scheme for the first Cyclone II device and the PS configuration scheme for the remaining Cyclone II devices (configuration slaves). Any other Altera® device that supports PS configuration can also be part of the chain as a configuration slave. In a multiple device chain, the nCONFIG, nSTATUS, CONF_DONE, DCLK, and DATA0 pins of each device in the chain are connected (see Figure 13–4). Figure 13–4 shows the pin connections for this setup.

Figure 15–6 shows a 484-pin Ultra FineLine BGA package outline.

Figure 15–6. 484-Pin Ultra FineLine BGA Package Outline